

03-31-2000



Docket No. 0819-0323

RECO

101302307

To the Honorable Commissioner of Patent and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): **Tetsuya UEDA, Eiji TAMAOKA & Nobuo AOI**

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: **Matsushita Electric Industrial Co., Ltd.**

Street Address: **1006, Oaza Kadoma, Kadoma-shi**

City **Osaka** State **Japan** ZIP **571-8501**

Additional name(s) & addresses(es) attached? ☐ Yes ☒ No

3. Name of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: **March 9, 2000**

4. Application number(s) or patent number(s): U.S. Serial No. **09/479,243**

If this document is being filed together with a new application, the execution date of the application is: _____

Title: **METHOD OF FABRICATING SEMICONDUCTOR DEVICE**

A: Patent Application No.(s)

B: Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Eric J. Robinson, NIXON PEABODY LLP**

Street Address: **8180 Greensboro Drive, Suite 800**

City: **McLean** State: **Virginia** ZIP **22102**

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41):\$**40.00**

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit Account Number: **19-2380(0819-0323)**

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Eric J. Robinson

Name of Person Signing

Signature

3-15-2000

Date:

Total number of pages comprising cover sheet, attachments and document: **3**

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PATENT
REEL: 010641 FRAME: 0342

ASSIGNMENT

WHEREAS, Tetsuya UEDA, Eiji TAMAOKA, Nobuo AOI

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in METHOD OF FABRICATING SEMICONDUCTOR DEVICE for which the undersigned has (have):

- (a) filed an application for Letters Patent of the United States of America on January 7, 2000 having Serial No. 09/479,243; or
- (b) executed an application for Letters Patent of the United States of America on even date; and

WHEREAS, Matsushita Electric Industrial Co., Ltd. of 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501, Japan

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto the Assignee the full and exclusive right to the said invention in the United States of America and its territories and for all foreign countries, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

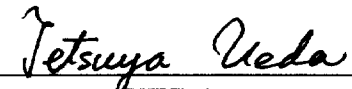
The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

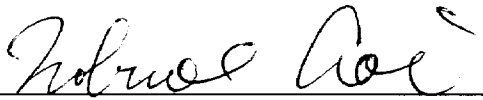
The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to the Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

This Assignment has been executed by the undersigned on the date(s) indicated.

Date: March 9, 2000, 
Tetsuya UEDA

Date: March 9, 2000, 
Eiji TAMAOKA

Date: March 9, 2000, 
Nobuo AOI

Date: _____, _____

Date: _____, _____

Date: _____, _____

Date: _____, _____

Date: _____, _____